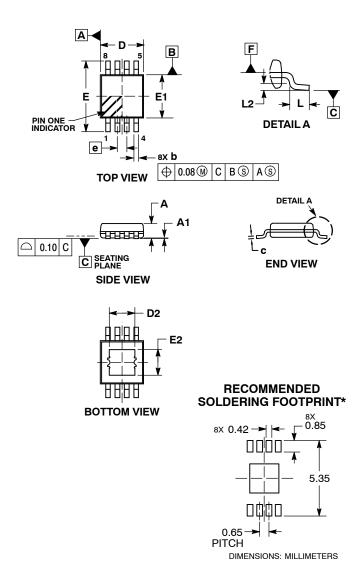


MSOP8 EP, 3x3 CASE 846AM ISSUE O

**DATE 27 FEB 2014** 



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## NOTES:

- DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
   CONTROLLING DIMENSIONS: MILLIMETERS.

- CONTROLLING DIMENSIONS: MILLIMETERS.
  DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
  ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10 MM IN
  EXCESS OF MAXIMUM MATERIAL CONDITION.
  DIMENSION D DOES NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR GATE BUBRS. MOLD FLASH,
  PROTRUSIONS, OR GATE BUBRS SHALL NOT EXCEED 0.15
  MM PER SIDE. DIMENSION E DOES NOT INCLUDE
  INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR
  PROTRUSION SHALL NOT EXCEED 0.25 MM PER SIDE.
  DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
  DATUMS A AND B TO BE DETERMINED AT DATUM F.
  A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE
  SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE
  BODY.

	MILLIMETERS		
DIM	MIN	MAX	
Α		1.10	
A1	0.05	0.15	
b	0.25	0.40	
c	0.13	0.23	
D	2.90	3.10	
D2	1.78 REF		
E	4.75	5.05	
E1	2.90	3.10	
E2	1.42 REF		
е	0.65 BSC		
L	0.40	0.70	
L2	0.254 BSC		

## **GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code Α = Assembly Location

Υ = Year

W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present and may be in either location.

DOCUMENT NUMBER:	98AON82708F	Electronic versions are uncontrolled except when		
STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped		
NEW STANDARD:		"CONTROLLED COPY" in red.		
DESCRIPTION:	MSOP8 EP, 3X3	PAGE 1 OF 2		



DOCU	MENT	NUI	MBE	R:
10A8e	182708	3F		

PAGE 2 OF 2

		_
ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY J. LIU.	27 FEB 2014

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.